



Material Content Data Sheet



Sales Product Name		BTS142D		Issued		25. September 2017		
MA#		MA001111122						
Package		PG-TO252-3-11		Weight*		372.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.197	1.40	1.40	13951	13951
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		578	
	non noble metal	copper	7440-50-8	215.017	57.73	57.81	577252	578003
	non noble metal	aluminium	7429-90-5	1.499	0.40	0.40	4023	4023
wire	non noble metal	aluminium	7429-90-5	1.499	0.40	0.40	4023	4023
encapsulation	organic material	carbon black	1333-86-4	1.233	0.33		3311	
	plastics	epoxy resin	-	21.583	5.79		57942	
	inorganic material	silicondioxide	60676-86-0	100.513	26.98	33.10	269846	331099
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10041	10041
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	244	245
solder	non noble metal	tin	7440-31-5	0.083	0.02		222	
	noble metal	silver	7440-22-4	0.103	0.03		277	
	non noble metal	lead	7439-92-1	3.943	1.06	1.11	10587	11086
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.15	5.16	51485	51552
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com